



HEPHY

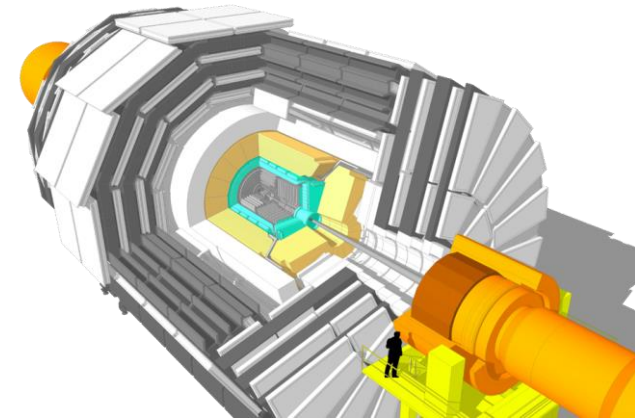
INSTITUT FÜR HOCHENERGIEPHYSIK

CMS Tracker & HGCal

Phase II Construction

Long Shutdown 3 (LS3) scheduled for 2025-2027?!!?

- LHC accelerator upgrade to High-Luminosity (HL)-LHC
- Upgrade of detectors necessary
 - Existing systems reach end of life (radiation damage)
 - Increase in luminosity at HL-LHC: 300 → 3000 fb⁻¹
- *Latest schedule with no COVID related delays*
 - *And experiments will not be ready by 2027 ...*



Long Shutdown 3 (LS3) scheduled for 2025-2027?!?

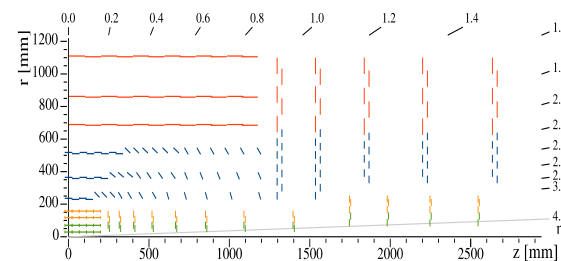
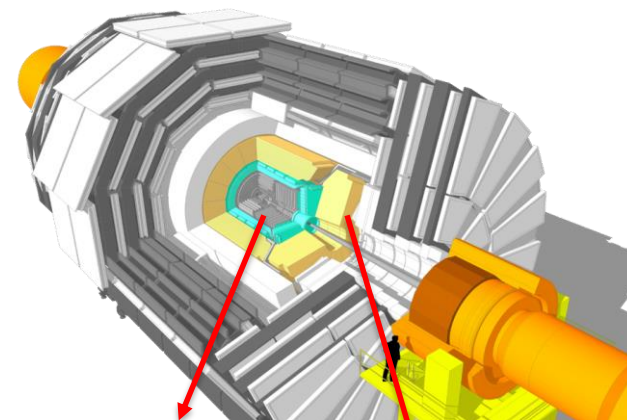
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 - Existing systems reach end of life (radiation damage)
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Phase-II Upgrade of CMS (with HEPHY involvement):

- **CMS Tracker**
→ 200 m² Si Sensors needed
- **High Granularity Calorimeter**
→ 600 m² Si Sensors (8 inch)

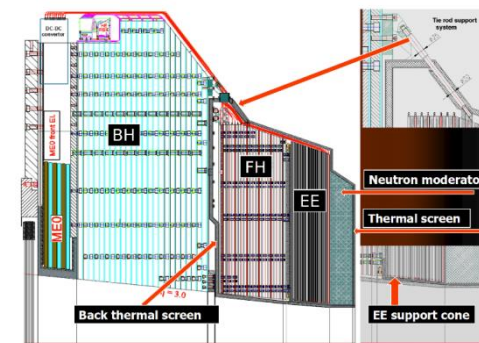
With our expertise in silicon sensors HEPHY plays a key role in *both* projects

- Simulations and design of sensors and test structures
 - Electrical characterization of sensors and test structures
 - Preparation, negotiations and QA of series production
- Co-Convenors of both sensor development working groups



Layout of Phase II Tracker

Layout of Endcap Calorimeter



Active contributors today

- Staff Scientists
 - **Marko Dragicevic**
 - Convener: Outer Tracker Sensors WG
 - Tracker Resource Manager
 - **Thomas Bergauer**
 - Convener: HGCal Sensors WG
 - Also: Group Leader Detector Development (non-CMS)
- PhDs
 - **Dominic Blöch**: Tracker SQG (ÖAW funded until Oct 2020)
 - **Viktoria Hinger**: Tracker & HGCal PQG (FFG funded until Oct 2020)
 - **Peter Paulitsch**: HGCal (FFG funded until mid 2021)
 - **Konstantinos Damanakis**: Sensor QA (ÖAW funded since Oct. 2020)
- PostDocs
 - **Florian Pitters**: HGCal & Detector Development
Left for paternity leave and to industry
 - **Moritz Wiehe**: HGCal
Since mid August 2021
- Sensor QA team
 - Margit Oberegger
 - Andreas Bauer
 - Stefan Schultschik
 - Doris Wohlmuth
July – October 2021
- Additional support
 - Wolfgang Brandner
 - Florian Buchsteiner

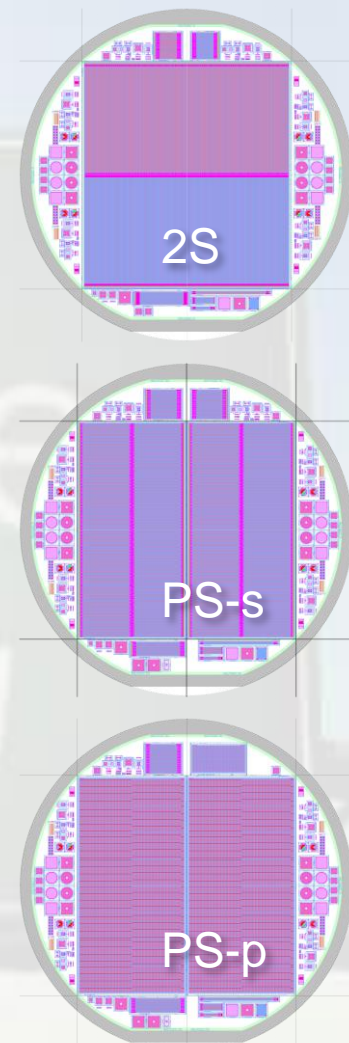


Note: In 2015, after long internal discussions and with the SAB, we decided to contribute to sensors only!

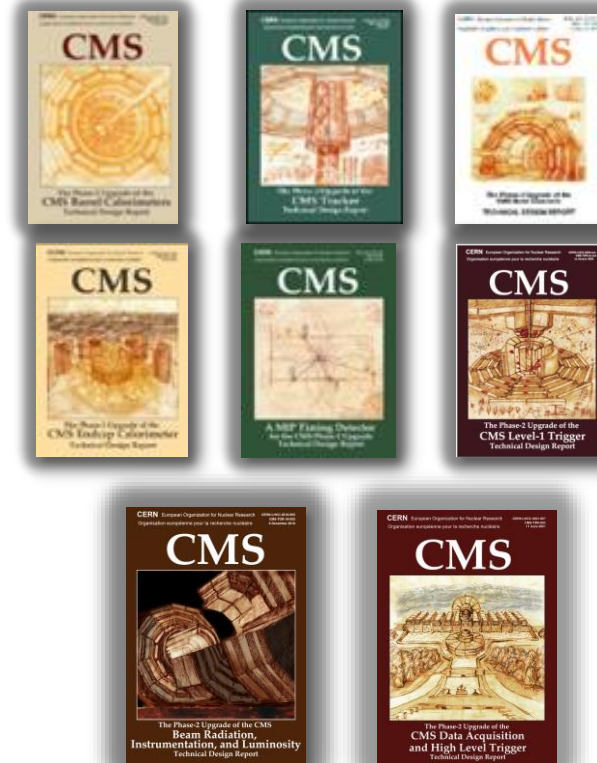
- HEPHY responsibilities in CMS Outer Tracker
 - **2010 – 2019:** *Participation in all development studies of the sensors* (Materials, thickness, radiation hardness, simulations, production process, design choices, etc.)
 - **2008 – 2018:** *Establishing alternative European sensor producer (Infineon)*
 - Stopped by Infineon in 2018 due to commercial reasons
 - **2019:** *Final design and wafer layout for all three sensor types* (PS-p pixel design from KIT)
 - **2014 – 2019:** *Conduction of the procurement process (~18 MCHF)*
 - **2019 – 2024:** *Definition and supervision of the Quality Assurance Campaign to produce ~ 29.000 sensors*
 - Process Quality Control (PQC) as major contribution from HEPHY (Viktoria Hingers PhD Thesis)

- HEPHY responsibilities in CMS HGCal
 - **2015 – 2018:** *Establishing alternative European sensor producer (Infineon)*
 - Initially our main interest to join HGCal
 - Infineon's 8" sensor technology was highly attractive for HGCal
 - Pushed HPK into developing 8" process for HGCal in parallel
 - **2018 – 2022:** *Development of radiation hard HGCal sensors with HPK* (Materials, thickness, radiation hardness, simulations, production process, design choices, etc.)
 - **2022 – 2024:** Participate in Quality Assurance campaign
 - Process Quality Control (PQC) as major contribution from HEPHY (Viktoria Hingers PhD Thesis)

- Managerial responsibilities
 - **Thomas Bergauer**
 - since 2016: Co-Convener of the HGCal Sensor WG
 - **Marko Dragicovic**
 - Since 2014: Co-Convener of the Tracker Sensor WG
 - Since 2017: Tracker Resource Manager



- TDRs¹ for all major Phase 2 upgrades completed and reviewed by LHCC
 - Tracker since 2017
 - HGCal since 2018
- MoUs² defined and signatures still in progress
 - MTD, BRIL and DAQ/HLT outstanding
- Tracker has recently passed the EDR³ for the Outer Tracker

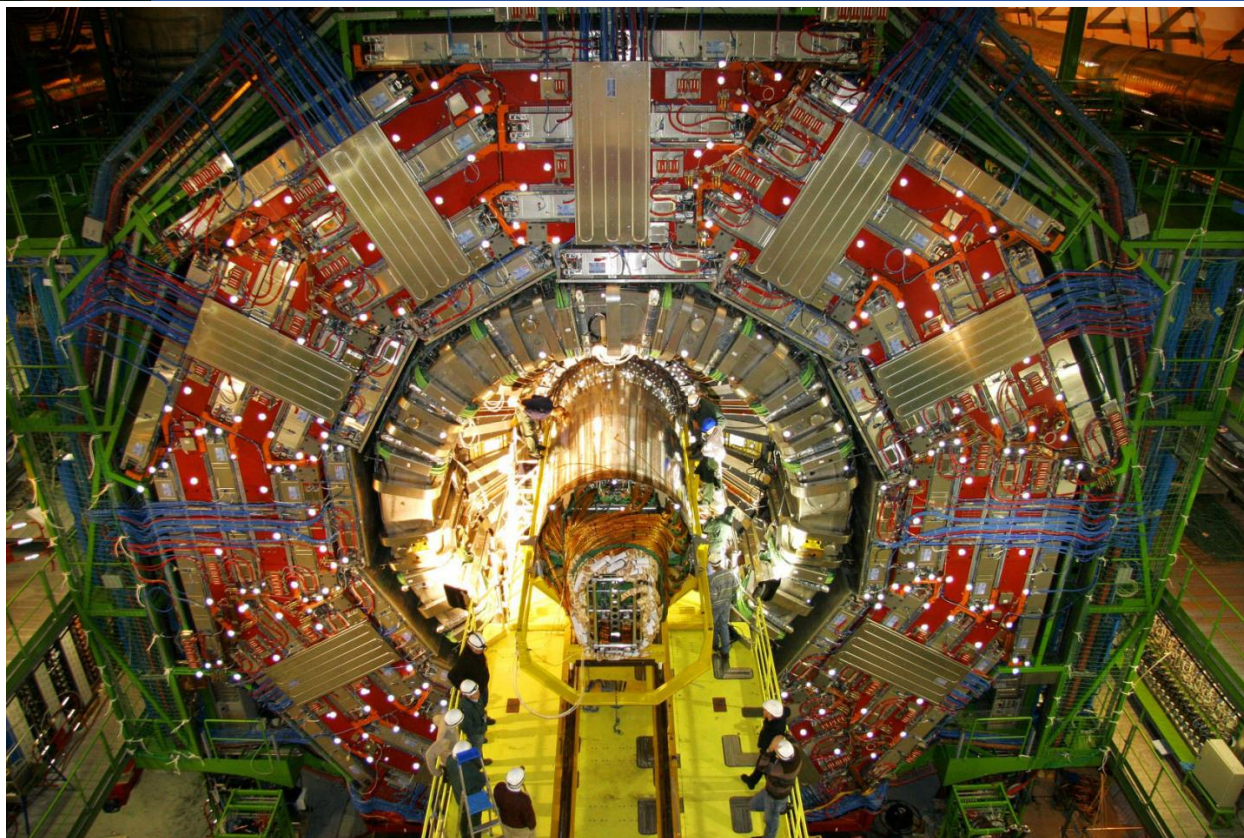


¹ Technical Design Report – Comprehensive description and motivation of the detector design with some details not yet fixed

² Memorandum of Understanding - defining technical and financial responsibilities of each Funding Agency in the construction of a subdetector

³ Engineering Design Review - CMS internal review to authorise the construction of significant parts of the detector

Phase-2 Upgrade MoU Addenda Signatory Progress					
Concerning	No.	Addendum	Last signed MoU Addendum received on 19/11/2021	Out of	Remaining
Common Fund	10	CERN-MoU-2017-060	30	56	26
Tracker	11	CERN-MoU-2019-006	13	22	9
Barrel Calorimeter	12	CERN-MoU-2019-007	5	8	3
Muons	13	CERN-MoU-2019-008	10	22	12
HGCal	14	CERN-MoU-2019-009	11	23	12
MoU Extension	15	CERN-MoU-2019-036	29	55	26
L1-Trigger	16	CERN-MoU-2020-319	3	12	9
Totals			101	198	97



CERN European Organization for Nuclear Research
Organisation européenne pour la recherche nucléaire

CERN-LHCC-2017-009
CMS-TDR-17-001
1 July 2017

CMS

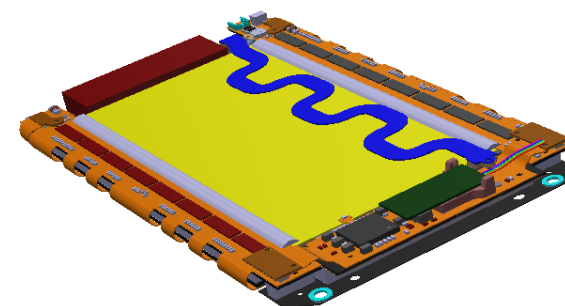
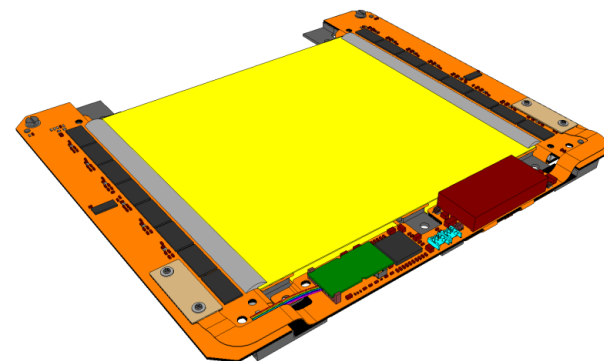


The Phase-2 Upgrade of the
CMS Tracker
Technical Design Report

OUTER TRACKER

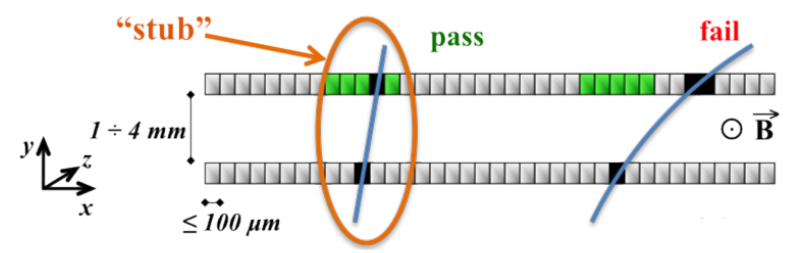
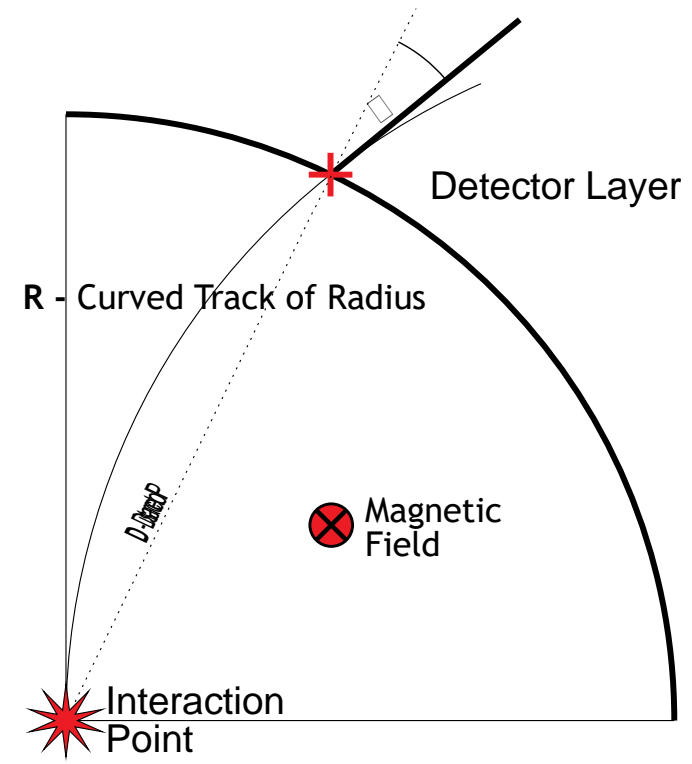
- Challenges for HL-LHC tracking
 - Harsh radiation environment up to
 - IT max.: $3.5 \times 10^{16} n_{eq}/cm^{-2}$, 1.9 Grad
 - OT max.: $1.1 \times 10^{15} n_{eq}/cm^{-2}$, 77 Mrad
 - High pileup
 - Increase granularity for sufficient two track separation
 - L1 Trigger needs tracking information
 - Tracker needs to provide data to L1 Trigger at every BX
 - Transmitting full information at every BX not possible, data reduction is required
- Goal: Keep performance of existing system in HL-LHC environment for 3000 fb^{-1} (ultimate 4000 fb^{-1})

- Fully integrated modules
 - Just add services (HV, LV, CO₂ cooling, readout and control links, mechanical mounting)
 - Filtering on high p_t tracks on module
- Just two types of modules used everywhere
 - Barrel and endcaps!
 - 2 and 3 different flavours (sensor spacing)



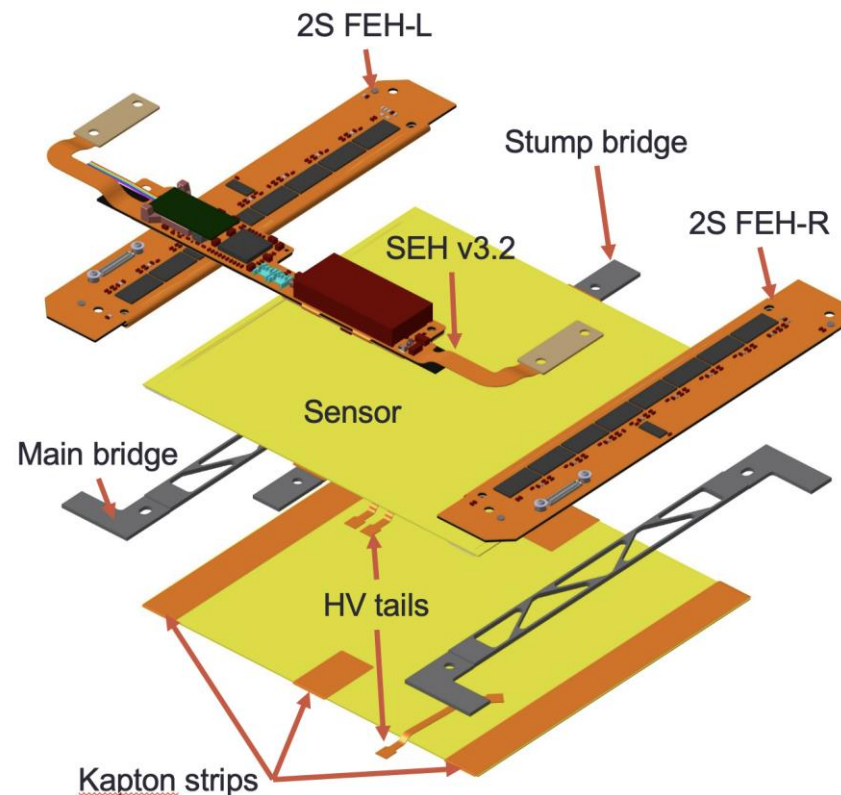
On-module data reduction by only sending hits from particles with a transverse momentum p_t of $>$ a few GeV/c

- At given magnetic field the track **curvature** depends on the **particle's p_t**
- **Different curvature** results in **different incident angles** at a given radius
- Estimate **incident angle** from **hit displacement** over a short distance
→ two parallel sensor planes



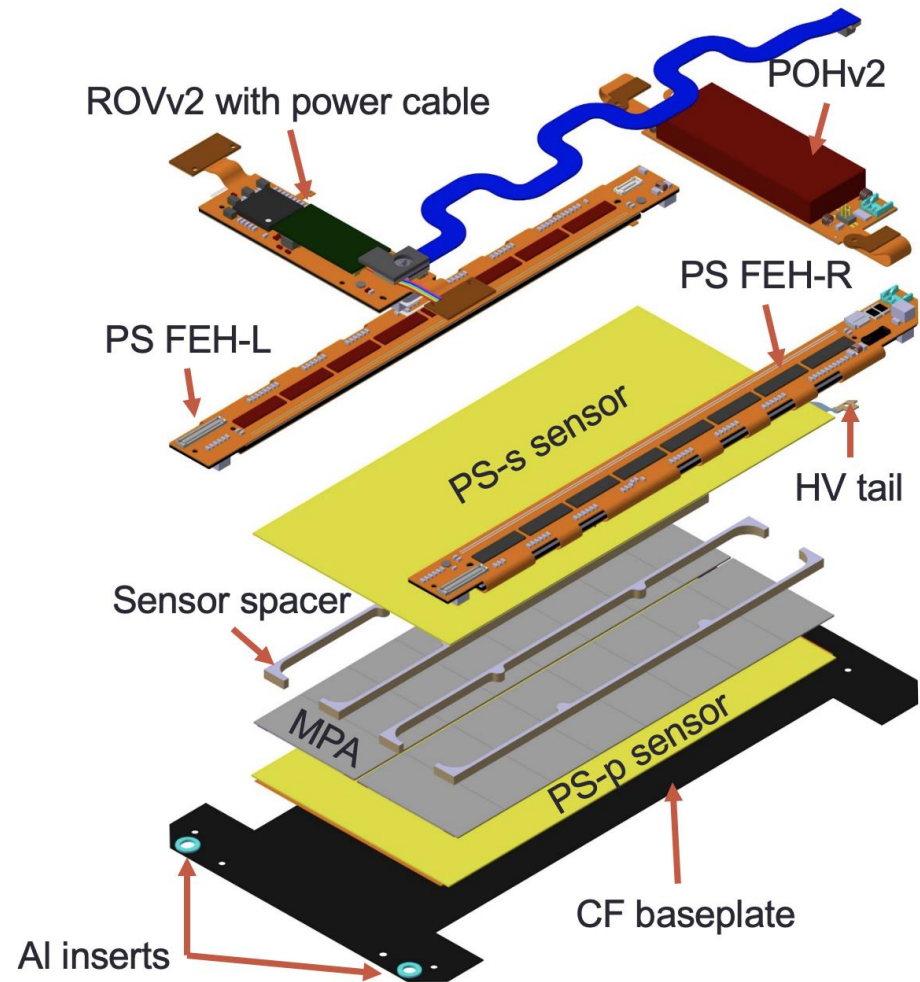
The 2S Module

- **2 x Strip sensors: 2S sensor**
 - Size: 10 x 10 cm²
 - Pitch: 90 μm
 - Length: 5 cm
 - No. of strips per sensor: 2x1016
- **2 x 8 CMS Binary Chips: CBC**
 - 2x127 channels per chip
 - Bump bonded to flexible hybrid
 - Connects to top and bottom sensors
 - Interchip communication via hybrid
- **Concentrator ASIC: CIC**
 - collects data from 8 CBCs (half module)
- **Low Power GigaBit Transceiver *lpGBT + VTRx+***
 - Bandwidth: 5 Gb/s
- **2-stage DCDC powering**
 - 12 V to
 - 2.5 V (opto)
 - 1.25 V (ASICS)



The PS Module

- **MacroPixel sensor: PS-p sensor**
 - Size: 5 x 10 cm²
 - Pitch: 100 μm
 - Length: 1.5 mm
 - No. of pixels: 32x960
- **Strip sensors: PS-s sensor**
 - Size: 5 x 10 cm²
 - Pitch: 100 μm
 - Length: 2.5 cm
 - No. of strips: 2x960
- **2 x 8 Short Strip ASIC: SSA**
 - 120 channels per chip
 - Sends hits to MPA
 - Bump bonded to flexible hybrid
- **16 MacroPixel ASIC: MPA**
 - 120 x 16 pixels per chip
 - Bump bonded to MacroPixel sensor
 - Includes correlation logic
- **Concentrator ASIC: CIC**
 - collects data from 8 MPAs
- **Low Power GigaBit Transceiver
*lpGBT + VTRx+***
 - Bandwidth: 5 or 10 Gb/s
- **2 stage DCDC powering**
 - 12 V to
 - 2.5 V (opto)
 - 1.25 V (ASICs)
 - 1.05 V (MPA digital)



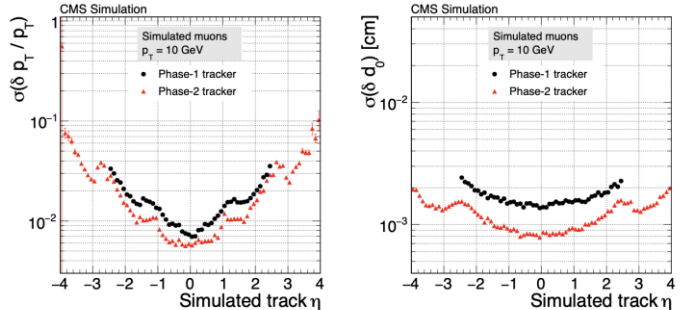
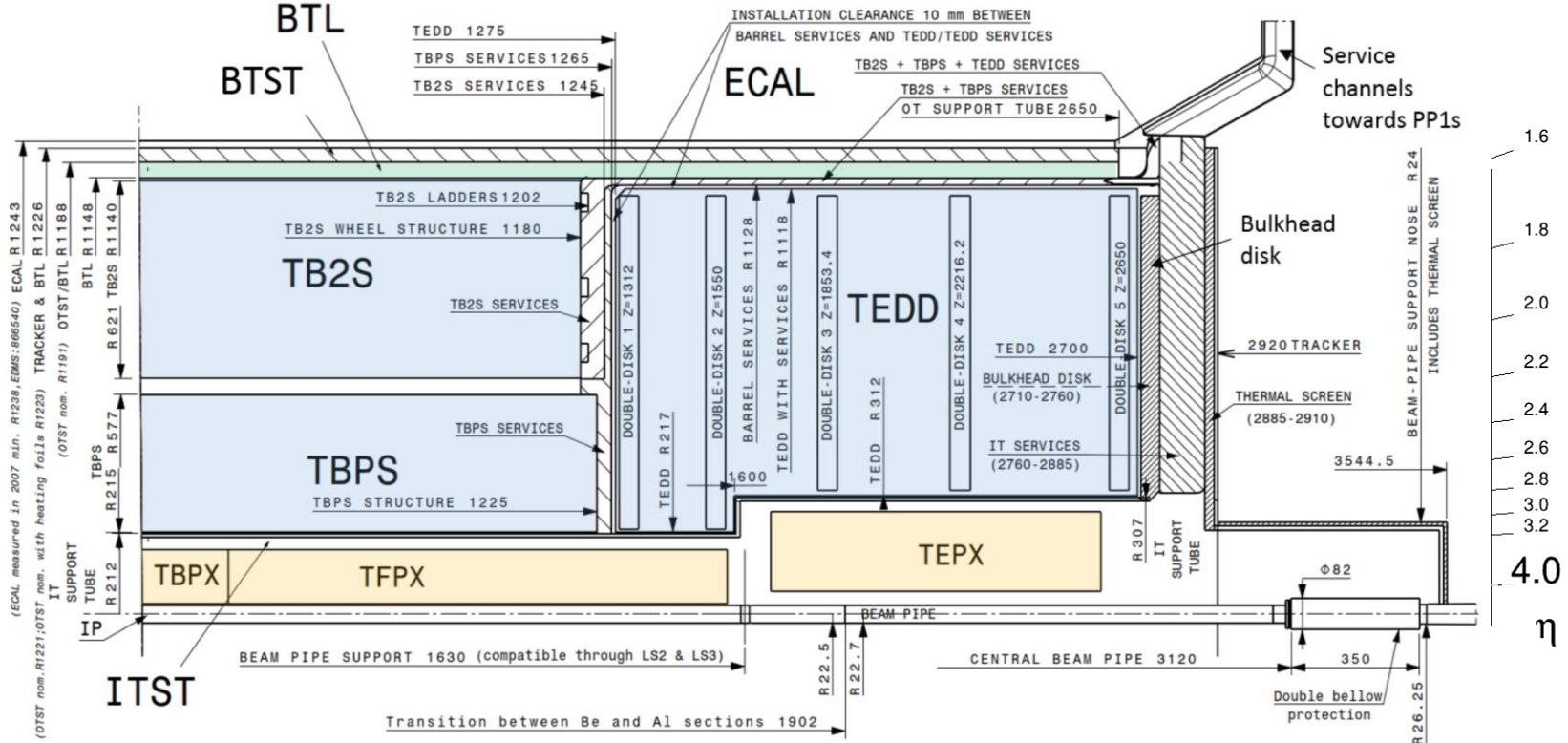


Figure 6.12: Relative resolution of the transverse momentum (left) and resolution of the transverse impact parameter (right) as a function of the pseudorapidity for the Phase-1 (black dots) and the upgraded (red triangles) tracker, using single isolated muons with a transverse momentum of 10 GeV.

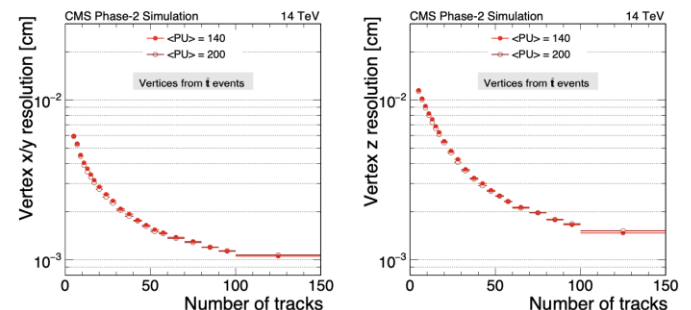
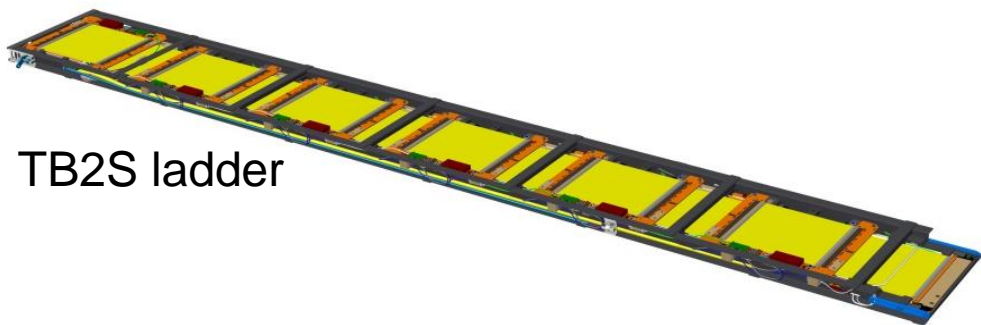
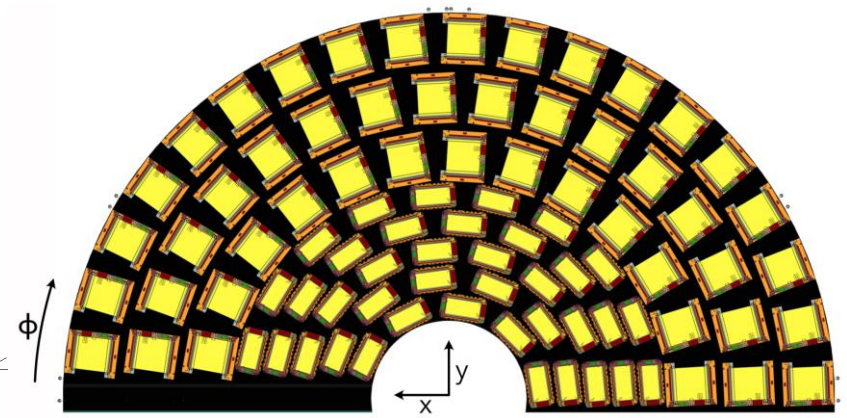


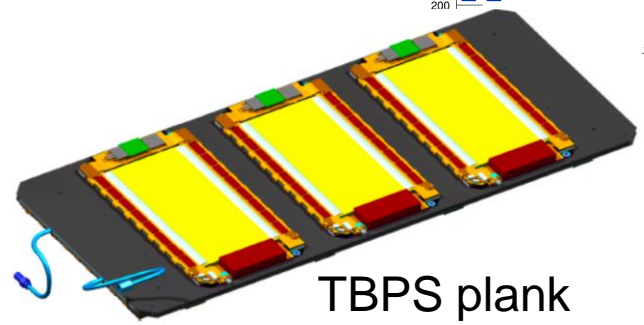
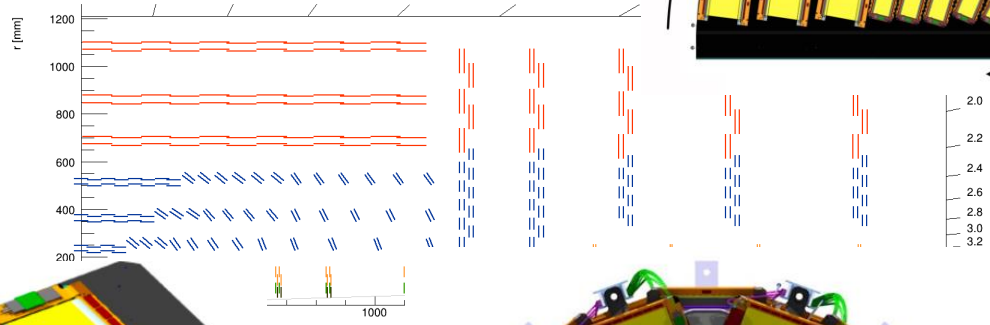
Figure 6.13: Vertex position resolution in x and y (left) and z (right) as a function of the number of tracks associated to the vertex, for t events with 140 pileup events (full circles) and 200 pileup events (open circles).



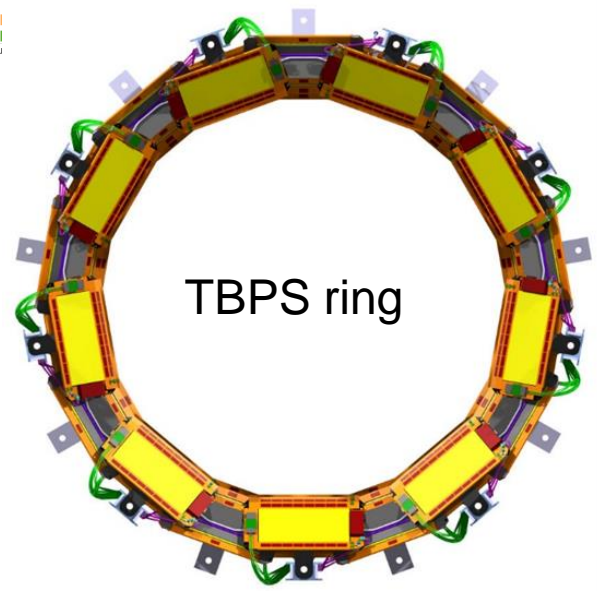
TB2S ladder



TEDD dee

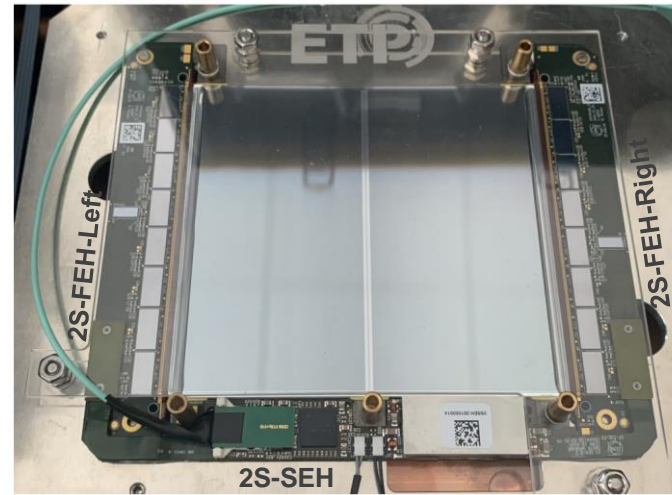
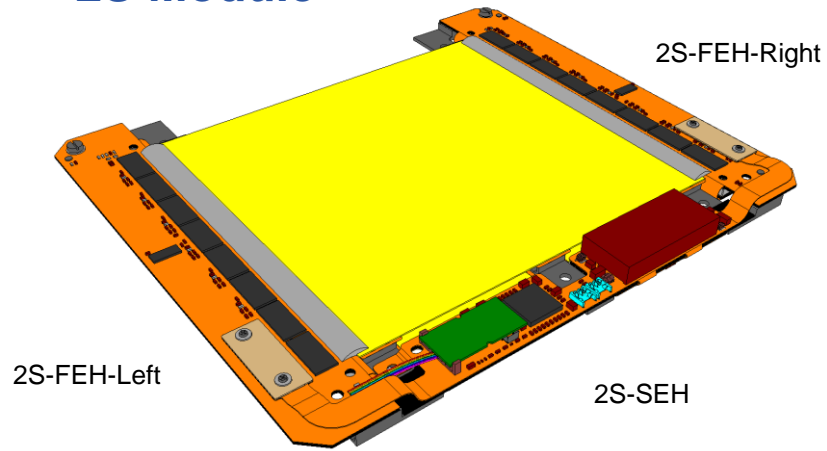


TBPS plank

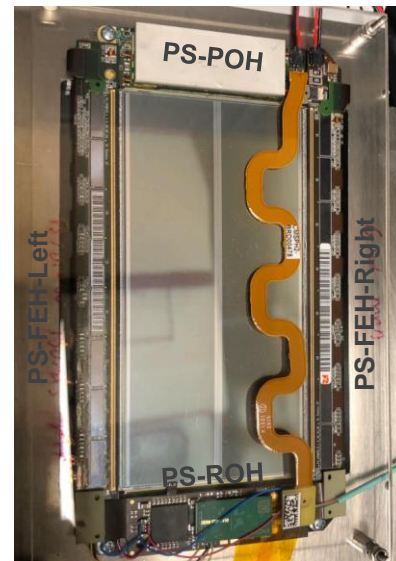
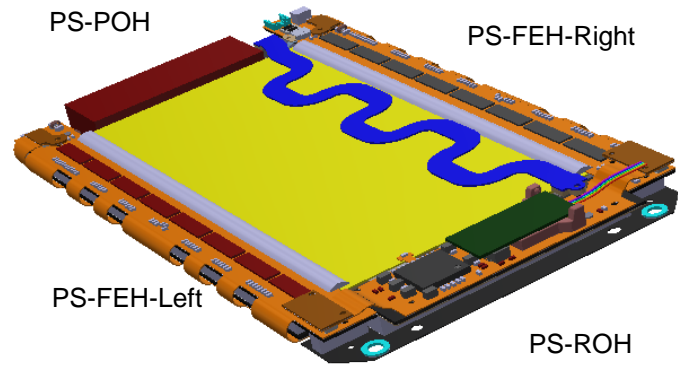


TBPS ring

2S Module



PS Module

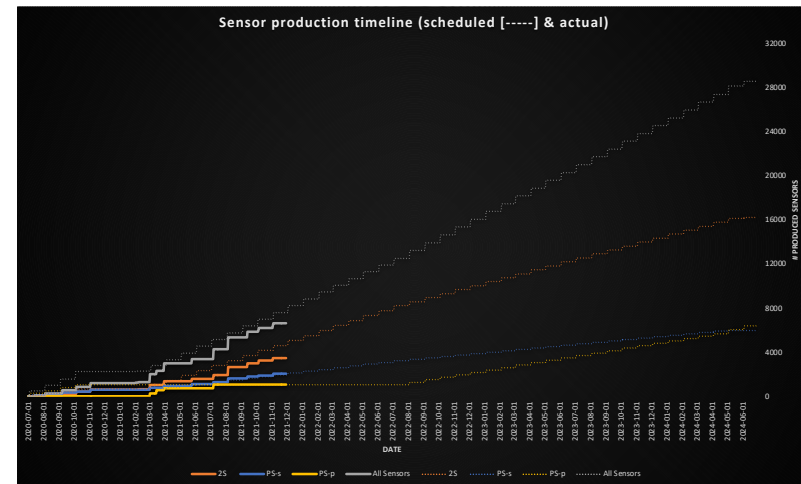
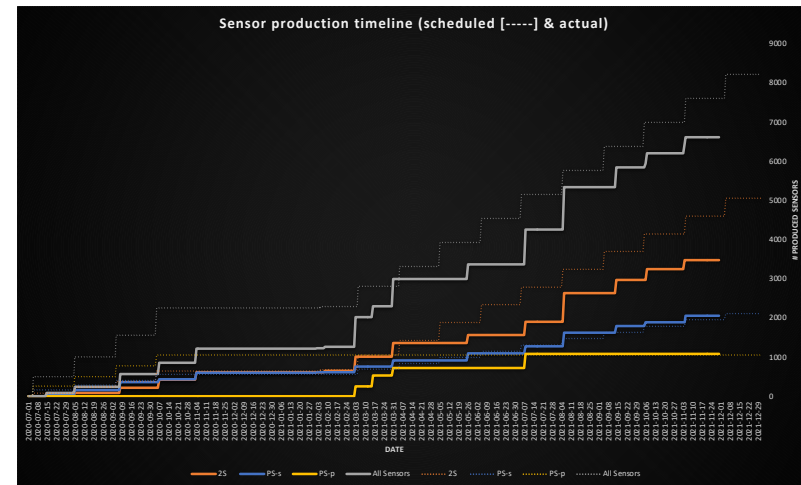


- Outer Tracker in transition to construction
 - Engineering Design Review (EDR) held on 14 – 15 October
<https://indico.cern.ch/event/1064838>
 - Authorised global production start for Outer Tracker
 - Specifically Hybrids, MaPSA and mechanics
 - Procurement Readiness Reviews (PRRs) already done for
 - Sensors (2019/20)
 - Raw composite materials CFRP, CF-foam, AICF (2020)
 - CBC production (2020)
 - MPA, SSA and CIC design and engineering run (2021)
 - Some components already in production since 2020
 - Sensors and CBC
- Production of modules will start next year

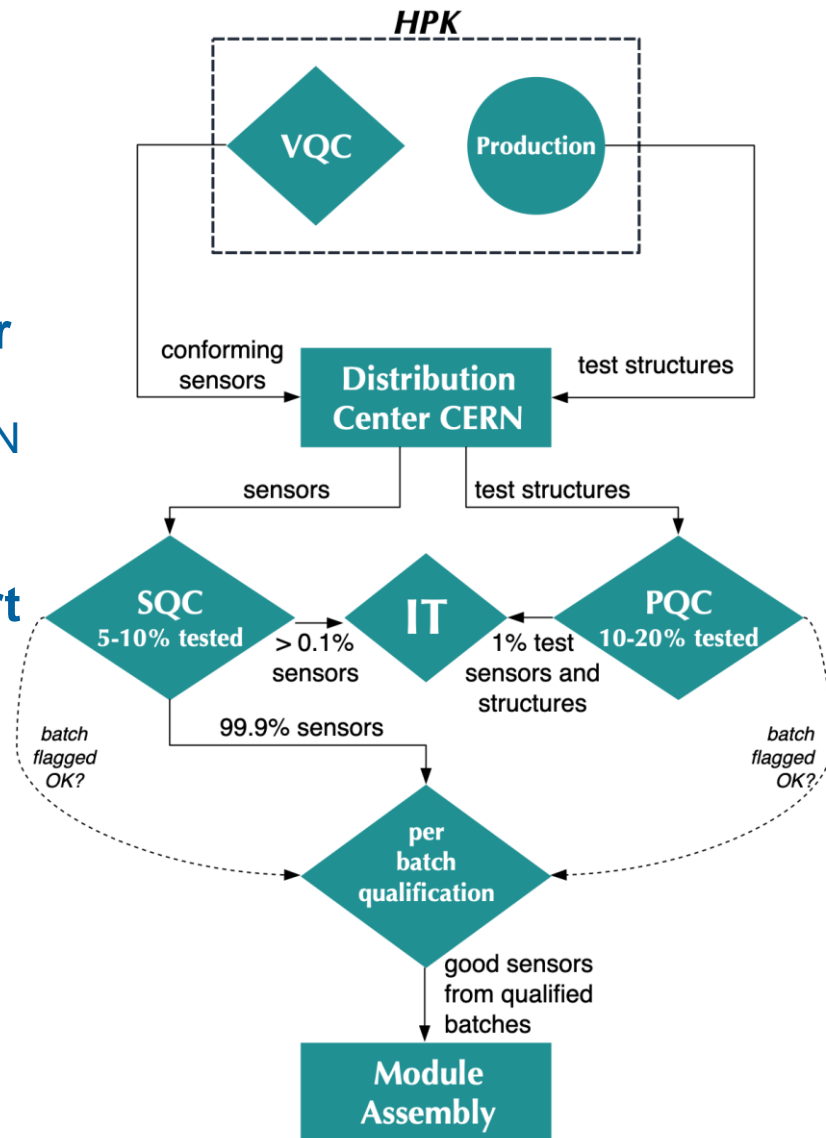


SENSOR PRODUCTION (AT HEPHY)

- **Sensor production (deliveries) started summer 2020**
 - Campaign started within COVID-19 pandemic
 - Lockdowns had significant effects on all centres
 - But all institutes pulled through
 - Several problems identified during pre-production and now corrected
- **Projected end date for production is mid 2024**
 - Almost 24.000 x 6" wafers
 - 16900 x 2S + 3100 x PS-s + 3750 x PS-p
- **Today:**
 - > 5000 wafers (> 20%) delivered
 - > 1200 sensors IV tested
 - > 500 sensors fully tested
 - > 3000 halfmoons tested

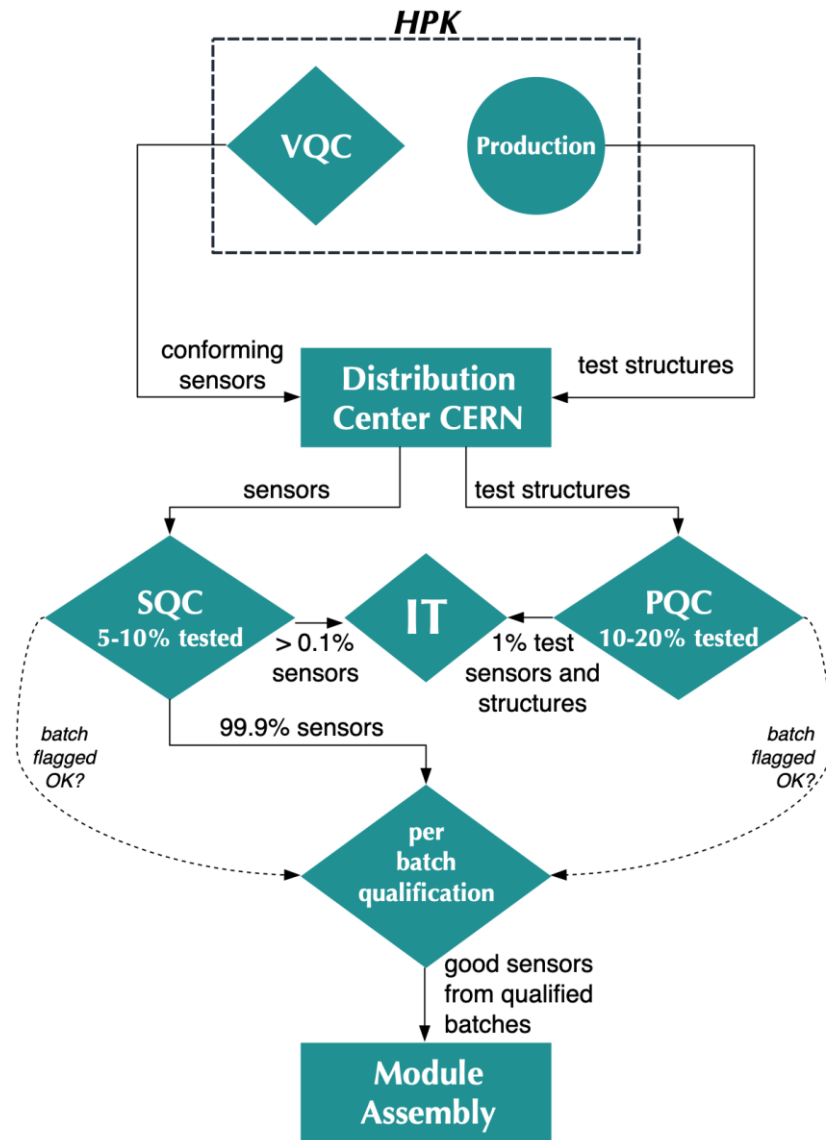


- Four tier quality control system
 - **VQC** - Vendor Quality Control
 - **SQC** - Sensor Quality Control
 - **PQC** - Process Quality Control
 - **IT** - Irradiation Tests
 - **All sensors** characterised by **producer**
 - Results recorded in DB for each sensor
 - Only conforming sensors are sent to CERN
 - Acceptance using **sample measurements** at SQC, PQC and IT
 - Production and QA monitored by **expert panel**
- Effort lead by HEPHY and KIT
- Participants
 - Europe: Demokritos, Perugia,
 - US: Brown, Rochester
 - Asia: Delhi, NCP Pakistan



HEPHY's responsibilities

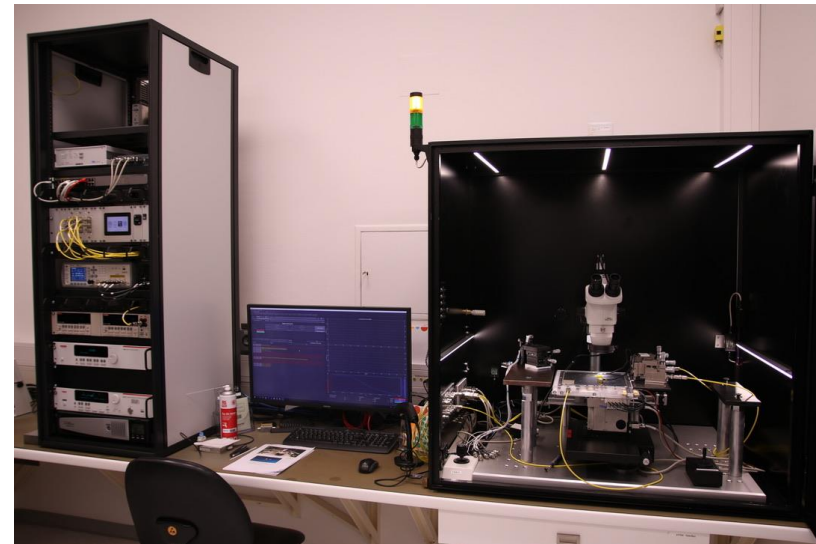
- Managerial tasks
 - Overall planning
 - Co-convener of weekly acceptance meetings (OTSEPP)
 - Contact to Tracker and CMS
 - Contact to Vendor (HPK)
- Sensor Quality Control (SQC)
 - Responsible for testing 25% of the production
- Process Quality Control (PQC)
 - Test structures, characterisation methods and setups developed at HEPHY
 - Responsible for testing 25% of the production



SENSOR QUALITY CONTROL

SQC AT HEPHY

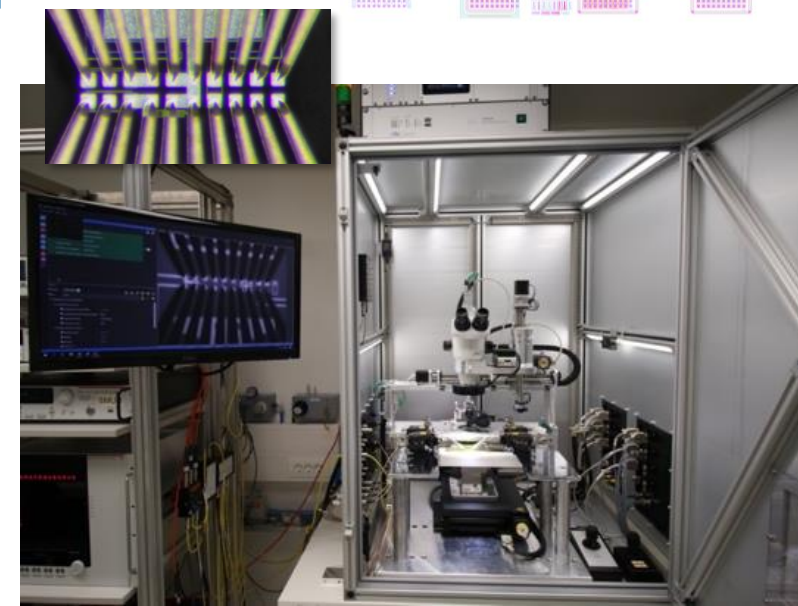
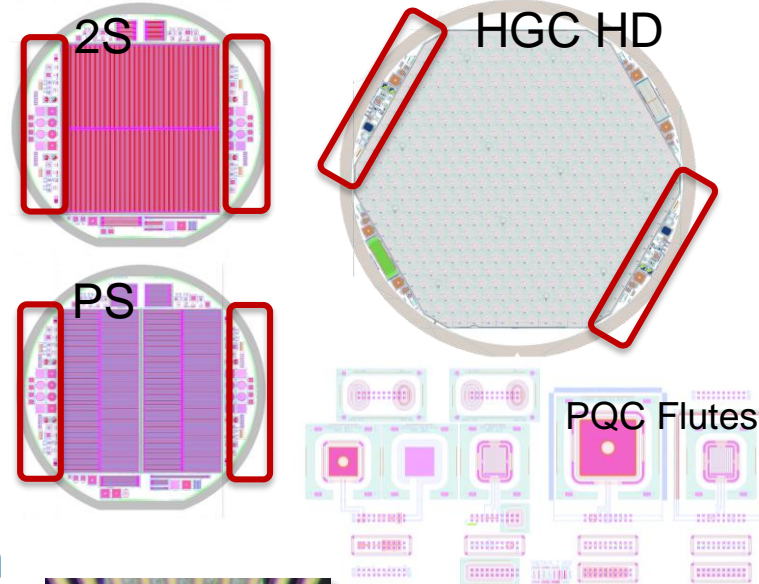
- **SQC – Sensor Quality Control:** fully characterise strip sensors
- Existing semiautomatic probe station **completely refurbished**
 - Fully custom made at HEPHY
 - Complex mechanical and electrical setup with precise environmental control and monitoring
 - Can automatically characterise ~2000 strips in 4-8 hours
- **Custom software** to control setup implemented in **Python**
 - Written by PhD Student (D. Blöch)
 - Important first step to phase out proprietary LabVIEW control
 - Plan to be replaced by more reliable Python tool implemented and maintained by Bernhard Arnold
 - Based on existing software tools by Bernhard for other setups like PQC
- Setup in operation **every day** to test one or two sensors
 - Mainly operated and maintained by Kostas and Stephan
 - Fully characterize at least 3 sensors per batch of ~40, one batch per week
- In addition, **longterm tests** are performed in our **climate chamber**
 - Including more detailed studies on humidity and temperature behaviour
- **After initial difficulties, HEPHY SQC is now among the fastest and most reliable!**



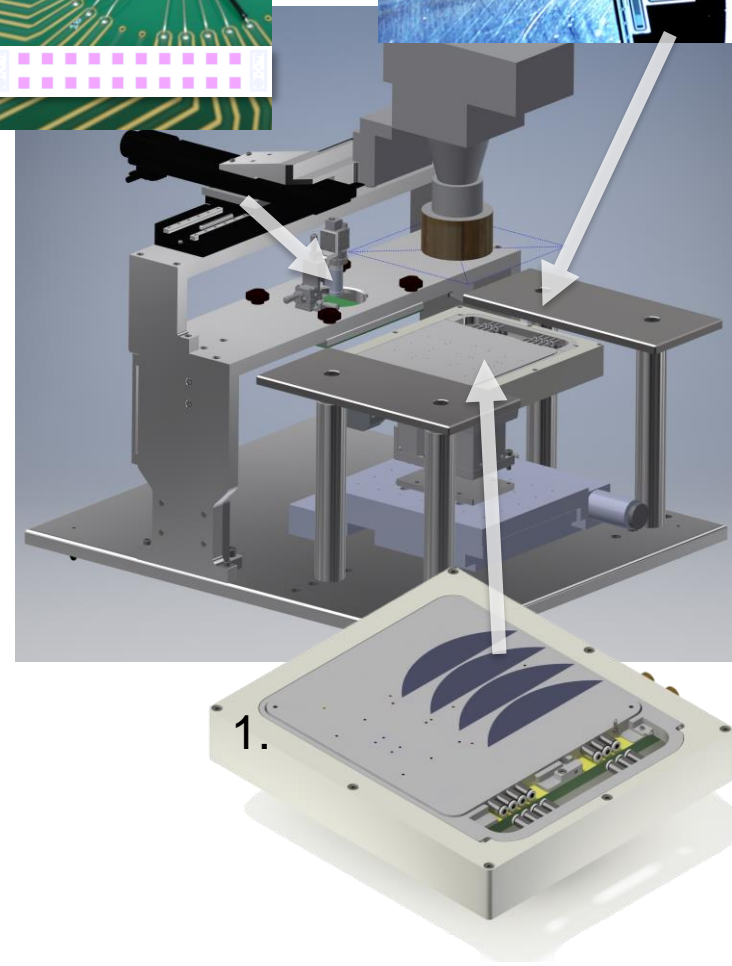
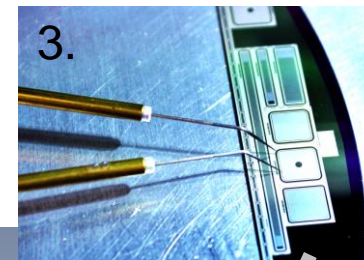
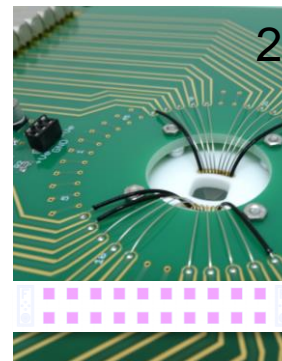
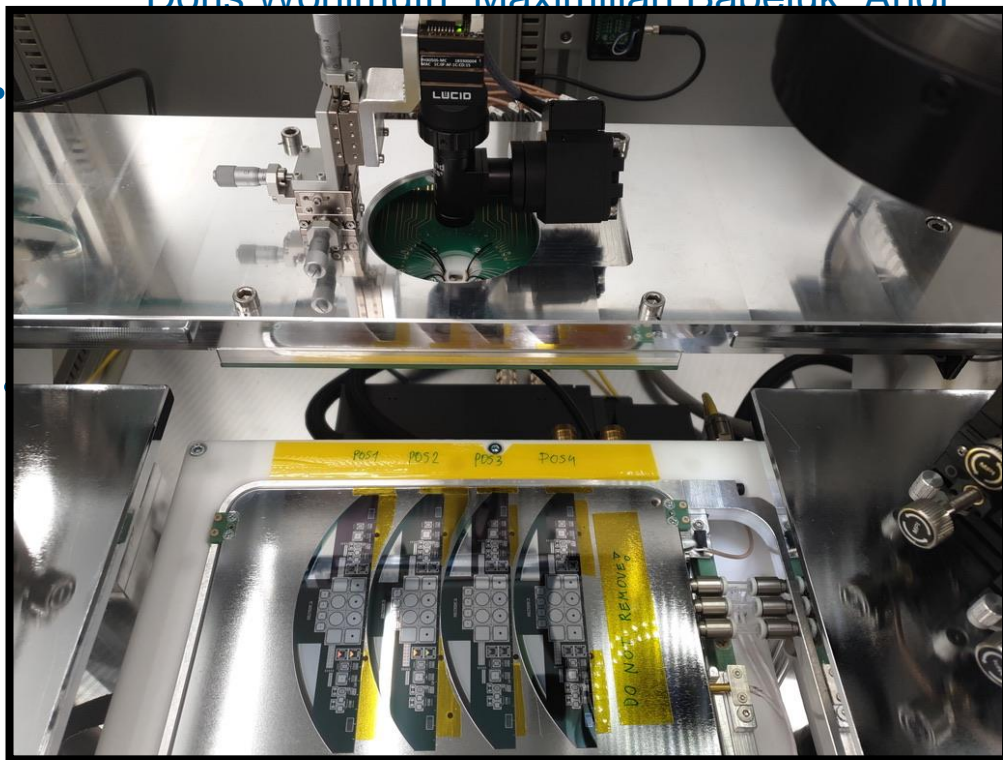
PROCESS QUALITY CONTROL

PQC AT HEPHY

- **PQC - Process Quality Control:** Use **test structures** to assess the **quality and stability** of the production process
 - 6" AC coupled (Tracker 2S and PS-s)
 - 6" DC coupled (Tracker PS-p)
 - 8" DC coupled (HGCal)
- **Identical** set of test structures on **all wafers**
- Use **standardised pattern** of 20 connection pads: **flute**
 - Connect using standardised probe cards
 - Use switching to access all structures on one flute
 - Automatic movement to next flute



- New **versatile semiautomatic** probe station
 - Built from scratch in 2019
 - Excellent support for design and manufacturing from HEPHY machine shop
 - Commissioning in 2020 difficult due to lockdowns
 - Now reliable working thanks a lot of effort: Doris Wohlmuth, Maximilian Babeluk, Andi



- PQC is providing **quick** and **detailed** check of process stability
 - First batches of sensor characterized within a week of delivery
 - Completed within a month
 - SQC usually lags behind a few weeks
- For each batch of ~40 wafers we perform **several 100 of measurements**
- All four Tracker PQC centers produce **consistent** results, **reliably** and **quickly**
- Also used to **understand** and **qualify** the **process** used for the future **HGCal production**

PQC Batch VP27079

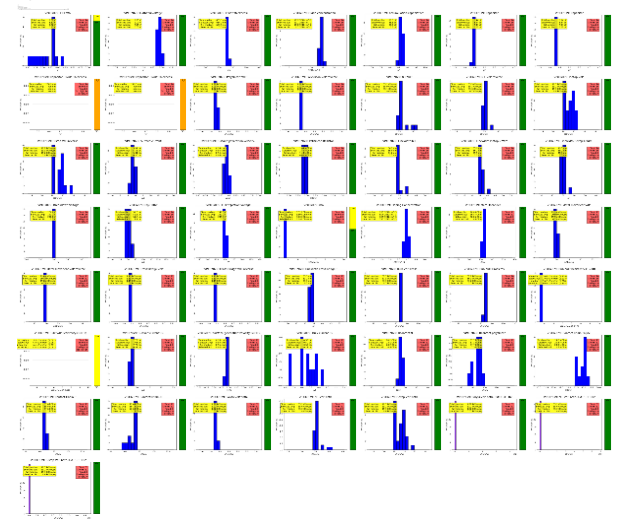
Table 1: Summary of sensor parameters for various wafers (e.g., WFA1, WFA2, WFA3, WFA4, WFA5, WFA6, WFA7, WFA8, WFA9, WFA10, WFA11, WFA12, WFA13, WFA14, WFA15, WFA16, WFA17, WFA18, WFA19, WFA20, WFA21, WFA22, WFA23, WFA24, WFA25, WFA26, WFA27, WFA28, WFA29, WFA30, WFA31, WFA32, WFA33, WFA34, WFA35, WFA36, WFA37, WFA38, WFA39, WFA40).

Table 2: Summary of sensor parameters for various wafers (e.g., WFA1, WFA2, WFA3, WFA4, WFA5, WFA6, WFA7, WFA8, WFA9, WFA10, WFA11, WFA12, WFA13, WFA14, WFA15, WFA16, WFA17, WFA18, WFA19, WFA20, WFA21, WFA22, WFA23, WFA24, WFA25, WFA26, WFA27, WFA28, WFA29, WFA30, WFA31, WFA32, WFA33, WFA34, WFA35, WFA36, WFA37, WFA38, WFA39, WFA40).

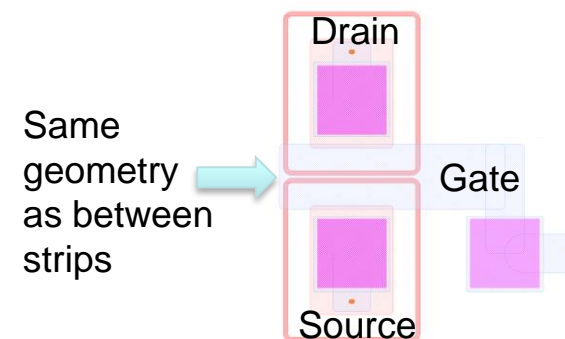
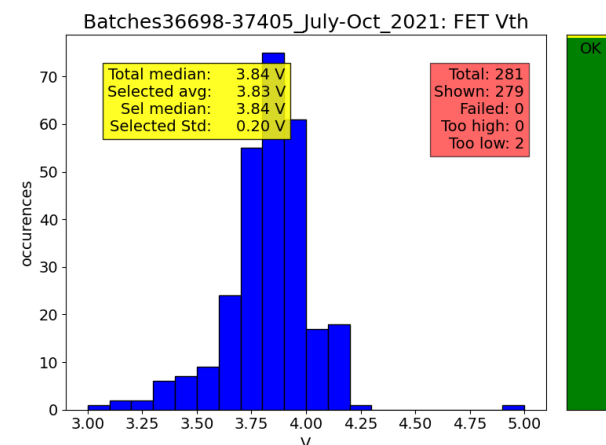
Table 3: Summary of sensor parameters for various wafers (e.g., WFA1, WFA2, WFA3, WFA4, WFA5, WFA6, WFA7, WFA8, WFA9, WFA10, WFA11, WFA12, WFA13, WFA14, WFA15, WFA16, WFA17, WFA18, WFA19, WFA20, WFA21, WFA22, WFA23, WFA24, WFA25, WFA26, WFA27, WFA28, WFA29, WFA30, WFA31, WFA32, WFA33, WFA34, WFA35, WFA36, WFA37, WFA38, WFA39, WFA40).

Table 4: Summary of sensor parameters for various wafers (e.g., WFA1, WFA2, WFA3, WFA4, WFA5, WFA6, WFA7, WFA8, WFA9, WFA10, WFA11, WFA12, WFA13, WFA14, WFA15, WFA16, WFA17, WFA18, WFA19, WFA20, WFA21, WFA22, WFA23, WFA24, WFA25, WFA26, WFA27, WFA28, WFA29, WFA30, WFA31, WFA32, WFA33, WFA34, WFA35, WFA36, WFA37, WFA38, WFA39, WFA40).

Summary data produced from standard characterisation of a single batch



- Some exemplary results from http://heros.local.hephy.at/pqc-results/INCOMING/analysis_Batches36698-37405_July-Oct_2021/results.html
- Doris analysed all measurements she performed between **July to October**
 - 281 Halfmoons characterised
 - Analysis done by script developed by Maximilian
- Example: **Threshold voltage** of a **FET** using inter-strip geometry inside channel
 - Representative and sensitive to strip isolation
- Perfect batches show values **around 3.8 V** with a healthy **~gaussian distribution**
- Some **weak batches** (not shown here) have **< 2 V**
 - But do not yet compromise strip isolation
→ FET threshold V is more sensitive
 - HPK informed and can take countermeasures



- **Outer Tracker construction** started and will be **in full swing** (module production) by end of 2022
- **Sensor production** ongoing **since 2020** with **HEPHY** leading the QA effort
- **High quality** of sensors delivered by HPK as **demonstrated and assured** by our measurements
- More **detailed** - and scientifically interesting - **investigations** starting now (not shown here)

→ *Now to Moritz with an update on HGCal*



**THANKS FOR YOUR
ATTENTION!**